

Features

- Ultra low capacitance: 0.6pF typical
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: ±15kV
Contact discharge: ±8kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 5A (8/20µs)
- RoHS Compliant

Mechanical Characteristics

- Package: MSOP-10
- Lead Finish: Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020



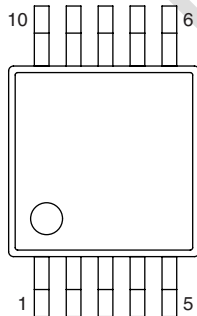
Applications

- DVI Ports
- USB 2.0 ports in PC or notebook
- IEEE 1394 ports

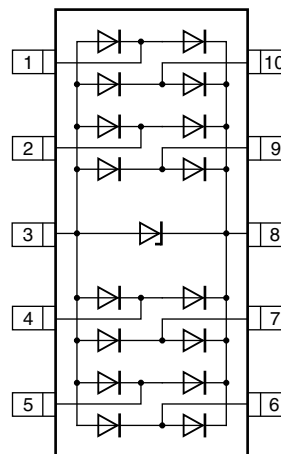
Ordering Information

Part Number	Qty per Reel	Reel Size
TPE0538M10	3000	13"

Dimensions and Pin Configuration



Pin Schematic



Circuit Diagram

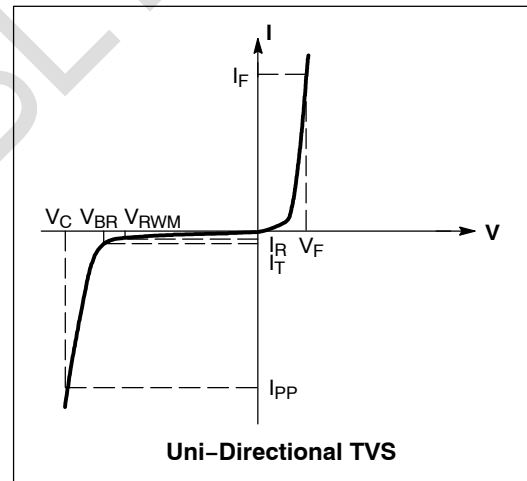
- 1 ESD protection I/O 1
- 2 ESD protection I/O 2
- 3 ground (GND)
- 4 ESD protection I/O 3
- 5 ESD protection I/O 4
- 6 ESD protection I/O 5
- 7 ESD protection I/O 6
- 8 supply voltage (V_{CC})
- 9 ESD protection I/O 7
- 10 ESD protection I/O 8

Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	100	W
Peak Pulse Current (8/20μs)	I _{PP}	5	A
ESD per IEC 61000-4-2 (Air)	VESD	±15	kV
ESD per IEC 61000-4-2 (Contact)		±8	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
I _T	Test Current
I _F	Forward Current
V _F	Forward Voltage @ I _F
P _{pk}	Peak Power Dissipation
C	Capacitance @ V _R = 0 and f = 1.0 MHz



Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			5	V	Any I/O pin to ground
Breakdown Voltage	V _{BR}	6			V	I _T = 1mA, any I/O pin to ground
Reverse Leakage Current	I _R			1	μA	V _{RWM} = 5V, any I/O pin to ground
Clamping Voltage	V _C			12	V	I _{PP} = 1A (8 x 20μs pulse), any I/O pin to ground
Clamping Voltage	V _C			20	V	I _{PP} = 5A (8 x 20μs pulse), any I/O pin to ground
Junction Capacitance	C _J		0.3	0.5	pF	V _R = 0V, f = 1MHz, between I/O pins
Junction Capacitance	C _J		0.6	0.8	pF	V _R = 0V, f = 1MHz, any I/O pin to ground

Typical characteristics ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Fig1. 8/20 μs Pulse Waveform

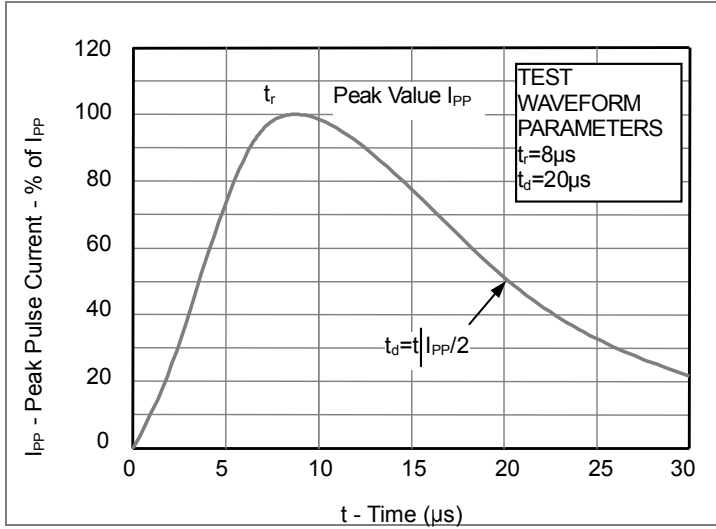


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

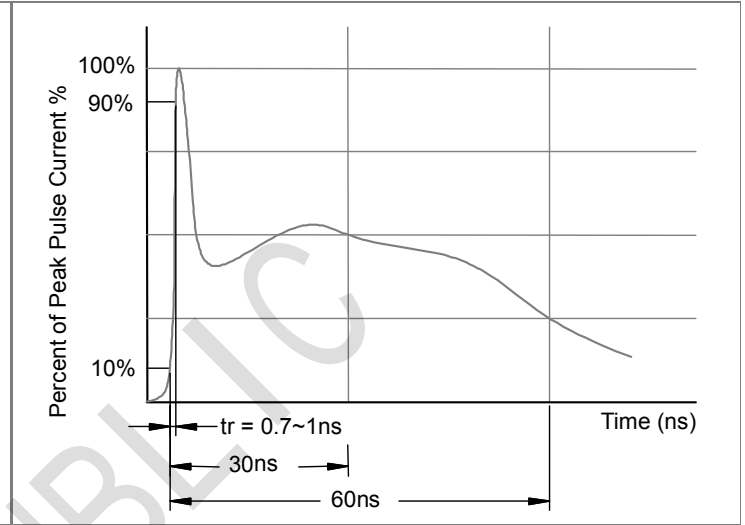
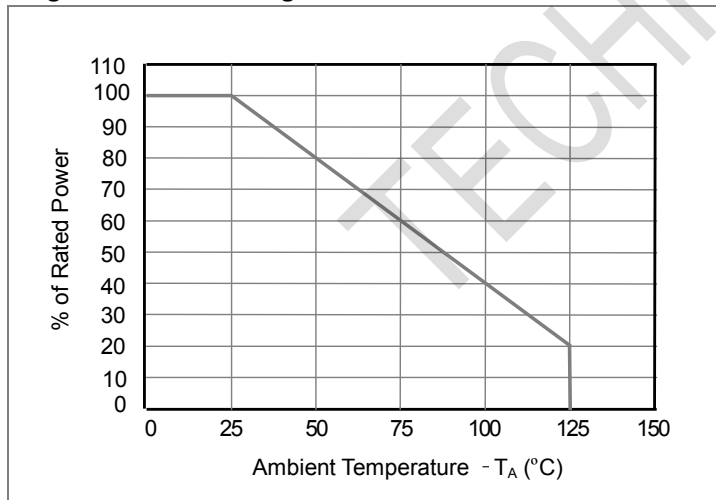
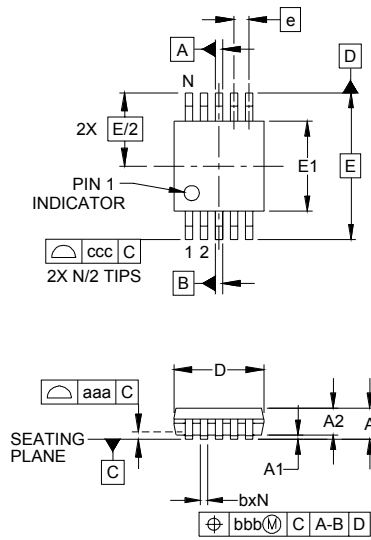


Fig3. Power Derating Curve

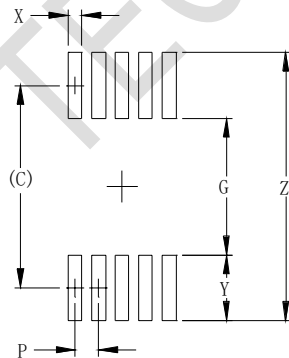


Outline Drawing -MSOP10



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	.043	-	-	1.10
A1	.000	-	.006	0.00	-	0.15
A2	.030	-	.037	0.75	-	0.95
b	.007	-	.011	0.17	-	0.27
c	.003	-	.009	0.08	-	0.23
D	.114	.118	.122	2.90	3.00	3.10
E1	.114	.118	.122	2.90	3.00	3.10
E	.193 BSC			4.90 BSC		
e	.020 BSC			0.50 BSC		
L	.016	.024	.032	0.40	0.60	0.80
L1	(0.037)			(0.95)		
N	10			10		
θ_1	0°	-	8°	0°	-	8°
aaa	.004			0.10		
bbb	.003			0.08		
ccc	.010			0.25		

Land Pattern -MSOP-10



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.161)	(4.10)
G	.098	2.50
P	.020	0.50
X	.011	0.30
Y	.063	1.60
Z	.224	5.70